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## REMARKS

Applicants appreciate the thorough examination of the present application as evidenced by the Final Office Action of October 10, 2006. In particular, Applicants appreciate the allowance of Claims 21-27. Allowed Claim 21 has been amended herein to correct an inadvertent typographical error therein. Applicants provide the present amendment accompanying a request for continued examination (RCE). In particular, Applicants have amended Claim 9 to further recite that the buried contact plug and the resistor are formed simultaneously and that the first and second pad contact plugs are formed simultaneously. Applicants respectfully submit that pending claims are in condition for allowance for at least the reasons discussed herein and respectfully request reconsideration and allowance thereof in due course.

Claims 9-20 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over United States Patent No. 6,500,724 to Zurcher *et al.* (hereinafter "Zurcher") in view of Admitted Prior Art. *See* Final Office Action, page 2. Applicants respectfully submit that many of the recitations of the pending claims are neither disclosed nor suggested by the cited combination. For example, amended independent Claim 9 recites, in part:

forming a buried contact plug on a cell array region of an integrated circuit substrate <u>and</u> forming a resistor on a peripheral circuit region of the integrated circuit substrate, **simultaneously**;

forming a first pad contact plug on the buried contact plug and forming a second pad contact plug on the resistor simultaneously...

Applicants respectfully submit that at least the highlighted recitations of independent Claim 9 are neither disclosed nor suggested by the cited combination for at least the reasons discussed herein.

The Final Office Action points to Zurcher as providing the highlighted teachings of independent Claim 9 set out above. *See* Final Office Action, pages 2-3. Zurcher discusses forming the buried contact plug 38 and the second pad contact plug 42 simultaneously and forming the resistor 32 and the first pad contact plug 44 simultaneously. In stark contrast, amended Claim 9 recites forming a buried contact plug ... and forming a resistor ..., <a href="mailto:simultaneously">simultaneously</a> and forming a first pad contact plug ... and forming a second pad contact plug ... <a href="mailto:simultaneously">simultaneously</a>. Accordingly, amended Claim 9 is patentable over the cited combination for at least these reasons.

Furthermore, Claim 15 recites, in part:

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forming an ohmic layer between a first pad contact plug and a buried contact plug in a cell array region of an integrated circuit substrate and between a second pad contact plug and a resistor in a peripheral circuit region of the integrated circuit substrate; and then

forming a capacitor on the first pad contact plug in the cell array region of the integrated circuit substrate; and

forming a metal contact plug on the second pad contact plug in the peripheral circuit region.

Applicants respectfully submit that the highlighted recitations of Claim 15 are neither disclosed nor suggested by the cited combination for at least the reasons discussed herein.

The Final Office Action points to Zurcher as providing the highlighted teachings of Claim 15 set out above. *See* Final Office Action, page 4. Zurcher in view of "admitted prior art" discusses forming the ohmic layer after the capacitor is formed and the capacitor of Zurcher is formed under the first pad contact plug. In stark contrast, Claim 15 recites forming the ohmic layer and then forming the capacitor. Thus, in accordance with some embodiments of the present invention, since the ohmic layer is formed prior to the capacitor, a possibility of the occurrence of a leakage current of the capacitor due to high temperatures imposed during formation of the ohmic layer may be reduced. Furthermore, Claim 15 recites forming the capacitor on the first pad contact plug, not under the first pad contact plug as discussed in Zurcher. Accordingly, Claim 15 is patentable over the cited combination for at least these reasons.

## CONCLUSION

Applicants respectfully submit that the pending claims are patentable over the cited references for at least the reasons discussed herein. Accordingly, Applicants respectfully request reconsideration and allowance of the pending claims in due course.

Respectfully submitted,

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CERTIFICATION OF ELECTRONIC TRANSMISSION

I hereby certify that this correspondence is being transmitted electronically to the U.S. Patent and Trademark Office on December 8, 2006 using the EFS.

Erin A. Campion